

SNx4AC244 3 ステート出力、オクタル・バッファまたはドライバ

1 特長

- 2V~6V の V_{CC} で動作
- 6V までの入力電圧に対応
- 最大 t_{pd} 7.5ns (5V 時)

2 アプリケーション

- サーバーとネットワーク・スイッチ
- LED ディスプレイ
- 通信インフラ
- モーター駆動制御ボード

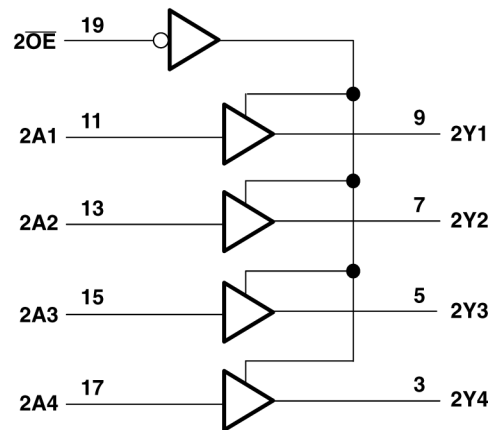
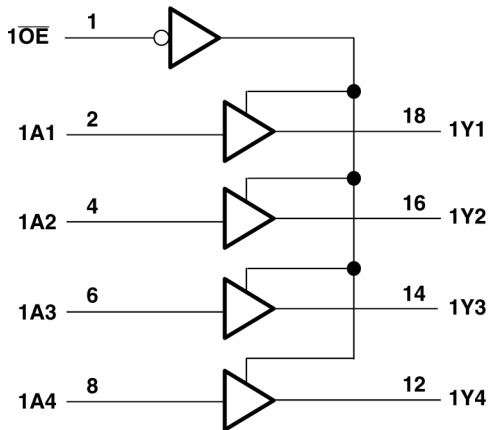
3 概要

これらのオクタル バッファ / ラインドライバは、3 ステートメモリ アドレス ドライバ、クロック ドライバ、バス用レシーバ / トランスミッタの性能と密度を向上することに特化して設計されています。

製品情報

部品番号	パッケージ ⁽¹⁾	パッケージ サイズ ⁽²⁾	本体サイズ ⁽³⁾
SN74AC244	DB (SSOP, 20)	7.2mm × 7.8mm	7.2mm × 5.3mm
	DGS (VSSOP, 20)	5.1mm × 4.9mm	5.1mm × 3mm
	DW (SOIC, 20)	12.8mm × 10.3mm	12.8mm × 7.5mm
	N (PDIP, 20)	24.33mm × 9.4mm	24.33mm × 6.35mm
	NS (SOP, 20)	12.6mm × 7.8mm	12.6mm × 5.3mm
	PW (TSSOP, 20)	6.5mm × 4.4mm	6.5mm × 4.4mm
	RKS (VQFN, 20)	4.5mm × 2.5mm	4.5mm × 2.5mm
SN54AC244	J (CDIP, 20)	24.2mm × 7.62mm	24.2mm × 6.92mm
	W (CFP, 20)	13.09mm × 8.13mm	13.09mm × 6.92mm
	FK (LCCC, 20)	8.89mm × 8.89mm	8.89mm × 8.89mm

- (1) 詳細については、[セクション 11](#) を参照してください。
- (2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。
- (3) 本体サイズ (長さ × 幅) は公称値であり、ピンは含まれません。



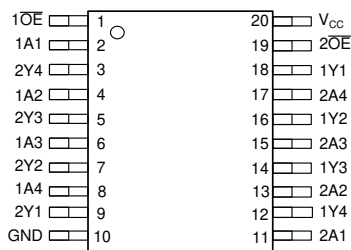
論理図 (正論理)



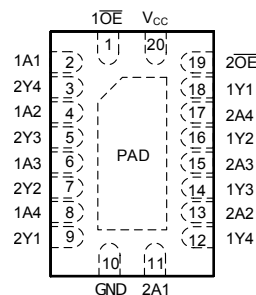
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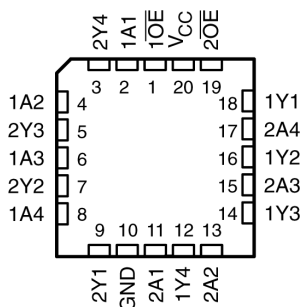
4 Pin Configuration and Functions



4-1. SN54AC244 J or W Package; SN74AC244 DB, DGS, DW, N, NS, or PW Package (Top View)



4-2. SN74AC244 RKS Package (Top View)



4-3. SN54AC244 FK Package (Top View)

表 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
1A1	2	I	Input
1A2	4	I	Input
1A3	6	I	Input
1A4	8	I	Input
1OE	1	I	Output enable
1Y1	18	O	Output
1Y2	16	O	Output
1Y3	14	O	Output
1Y4	12	O	Output
2A1	11	I	Input
2A2	13	I	Input
2A3	15	I	Input
2A4	17	I	Input
2OE	19	I	Output enable
2Y1	9	O	Output
2Y2	7	O	Output
2Y3	5	O	Output
2Y4	3	O	Output
GND	10	—	Ground
V _{CC}	20	—	Power pin
Thermal Pad ⁽²⁾	—	—	The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply.

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

(2) RKS package only

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I ¹	Input voltage range	-0.5	$V_{CC}+0.5$	V
V_O ¹	Output voltage range	-0.5	$V_{CC}+0.5$	V
I_{IK}	Input clamp current	$(V_I < 0 \text{ or } V_I > V_{CC})$		± 20 mA
I_{OK}	Output clamp current,	$(V_O < 0 \text{ or } V_O > V_{CC})$		± 20 mA
I_O	Continuous output current	$(V_O = 0 \text{ or } V_{CC})$		± 50 mA
	Continuous current through V_{CC} or GND			± 200 mA
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted) ¹

			SN54AC244		SN74AC244		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	6	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 4.5 V	3.15		3.15		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V	0.9		0.9		V
		V _{CC} = 4.5 V	1.35		1.35		
		V _{CC} = 5.5 V	1.65		1.65		
V _I	Input voltage		0	V _{CC}	0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V	-12		-12		mA
		V _{CC} = 4.5 V	-24		-24		
		V _{CC} = 5.5 V	-24		-24		
I _{OL}	Low-level output current	V _{CC} = 3 V	12		12		mA
		V _{CC} = 4.5 V	24		24		
		V _{CC} = 5.5 V	24		24		
Δt/Δv	Input transition rise or fall rate		8		8		ns/V
T _a	Operating free-air temperature		-55	125	-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND for proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

5.3 Thermal Information

THERMAL METRIC ⁽¹⁾		SNx4AC244							UNIT
		DB (SSOP)	DGS (VSSOP)	DW (SOIC)	N (PDIP)	NS (SOP)	PW (TSSOP)	RKS (VQFN)	
		20 PINS							
R _{θJA}	Junction-to-ambient thermal resistance	70	123.5	101.2	69	106.2	126.2	67.7	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC244		SN74AC244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.46		
		4.5 V	3.86			3.7		3.76		
	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		
		5.5 V				3.85				
V _{OL}	I _{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44	
		5.5 V					1.65			
I _I	Data inputs	V _I = V _{CC} or GND			±0.1		±1		±1	μA
	Control inputs	V _I = V _{CC} or GND			±0.1		±1		±1	
I _{OZ}	V _O = V _{CC} or GND, V _I (OE) = V _{IL} or V _{IH}		5.5 V		±0.25		±5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		80		40	μA
C _i	V _I = V _{CC} or GND		5 V		2.5					pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

5.5 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC244		SN74AC244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	2	6.5	9	1	12.5	1.5	10	ns
t_{PHL}			2	6.5	9	1	12	2	10	
t_{PZH}	$\overline{OE}$	Y	2	6	10.5	1	11.5	1.5	11	ns
t_{PZL}			2.5	7.5	10	1	13	2	11	
t_{PHZ}	$\overline{OE}$	Y	3	7	10	1	12.5	1.5	10.5	ns
t_{PLZ}			2.5	7.5	10.5	1	13	2.5	11.5	

5.6 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Figure 6-1](#))

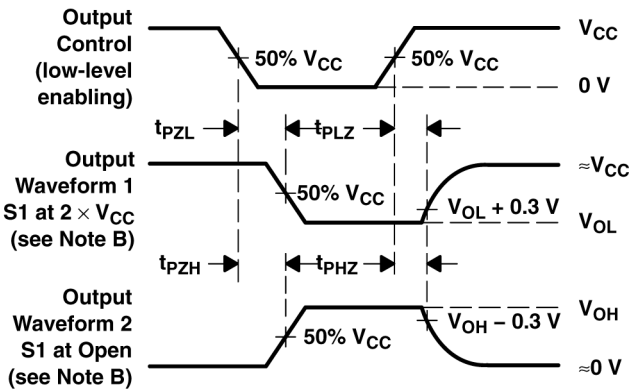
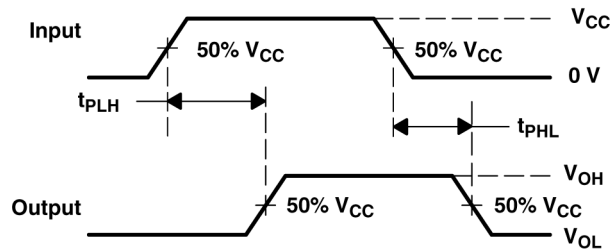
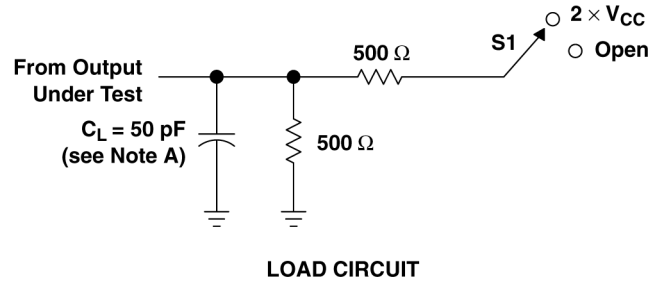
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC244		SN74AC244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	7	7	9.5	1	7.5	ns
t_{PHL}			1.5	5	7	7	9	1	7.5	
t_{PZH}	$\overline{OE}$	Y	1.5	5	7	7	9	1.5	8	ns
t_{PZL}			1.5	5.5	8	8	10.5	1.5	8.5	
t_{PHZ}	$\overline{OE}$	Y	2.5	6.5	9	9	10.5	1	9.5	ns
t_{PLZ}			2	6.5	9	9	11	2	9.5	

5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	$C_I = 50\text{ pF}$, $f = 1\text{ MHz}$	45	pF

6 Parameter Measurement Information



- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

图 6-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	Open

7 Detailed Description

7.1 Overview

The 'AC244 devices are organized as two 4-bit buffers or drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes non-inverted data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

For the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.2 Functional Block Diagram

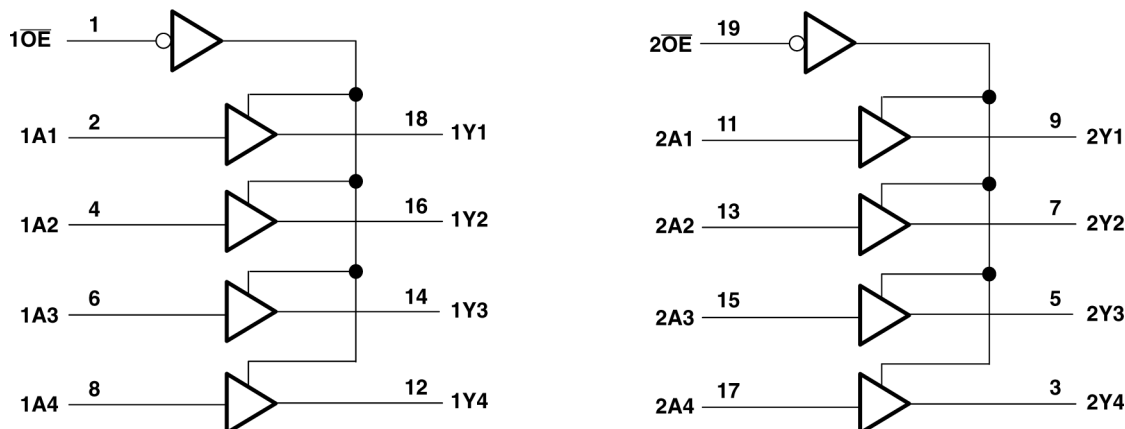


图 7-1. Logic Diagram (Positive Logic)

7.3 Device Functional Modes

表 7-1. Function Table (Each Buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

8 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Absolute Maximum Ratings* section. Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- μ F capacitor; if there are multiple V_{CC} terminals, then TI recommends a 0.01- μ F or 0.022- μ F capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1 μ F and 1 μ F are commonly used in parallel. The bypass capacitor must be installed as close as possible to the power terminal for best results.

8.2 Layout

8.2.1 Layout Guidelines

Reflections and matching are closely related to the loop antenna theory but are different enough to be discussed separately from the theory. When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self-inductance of the trace, which results in the reflection. Not all PCB traces can be straight; therefore, some traces must turn corners. [Layout example for SNx4AC244](#) shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

8.2.1.1 Layout Example

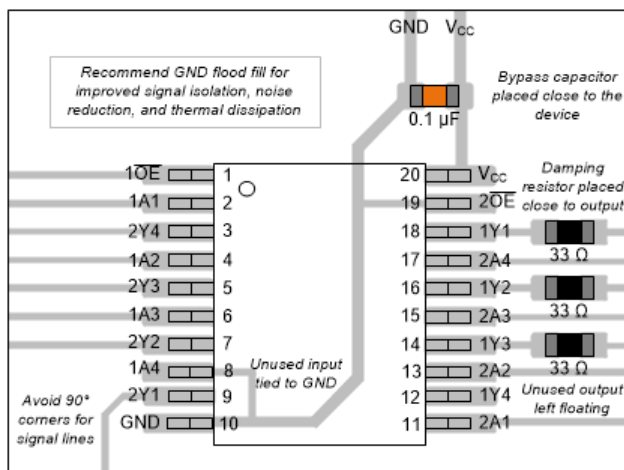


図 8-1. Layout Example for the SNx4AC244 in the PW Package

9 Device and Documentation Support

9.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.2 サポート・リソース

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9.5 用語集

[テキサス・インスツルメンツ用語集](#)

この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision G (August 2023) to Revision H (March 2024)	Page
• 「製品情報」表、「ピン構成および機能」セクション、「熱に関する情報」表に DGS パッケージを追加。「製品情報」表の J および W パッケージ サイズを更新.....	1
• Updated RθJA values: DW = 58 to 101.2, NS = 60 to 106.2, PW = 83 to 126.2, all values in °C/W	5
• Added <i>Application and Implementation</i> section.....	9

Changes from Revision F (May 2023) to Revision G (August 2023)	Page
• パッケージリード サイズを含めるよう「製品情報」表を更新	1
• RKS パッケージ情報を追加	1
• Updated high-level input voltage values in <i>Recommended Operating Conditions</i> table	4

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-87552012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87552012A SNJ54AC 244FK
5962-8755201RA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201RA SNJ54AC244J
5962-8755201SA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201SA SNJ54AC244W
5962-8755201VRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201VR A SNV54AC244J
5962-8755201VRA.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201VR A SNV54AC244J
5962-8755201VSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201VS A SNV54AC244W
5962-8755201VSA.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201VS A SNV54AC244W
SN74AC244DBR	NRND	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244DBR.A	NRND	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244DGSR	Active	Production	VSSOP (DGS) 20	5000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	AC244
SN74AC244DGSR.A	Active	Production	VSSOP (DGS) 20	5000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC244
SN74AC244DW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-40 to 85	AC244
SN74AC244DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC244N
SN74AC244N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC244N
SN74AC244NE4	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74AC244N
SN74AC244NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244NSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AC244PW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 85	AC244
SN74AC244PWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244PWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC244
SN74AC244RKSR	Active	Production	VQFN (RKS) 20	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AC244
SN74AC244RKSR.A	Active	Production	VQFN (RKS) 20	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AC244
SNJ54AC244FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-87552012A SNJ54AC 244FK
SNJ54AC244FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-87552012A SNJ54AC 244FK
SNJ54AC244J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201RA SNJ54AC244J
SNJ54AC244J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201RA SNJ54AC244J
SNJ54AC244W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201SA SNJ54AC244W
SNJ54AC244W.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8755201SA SNJ54AC244W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AC244, SN54AC244-SP, SN74AC244 :

- Catalog : [SN74AC244](#), [SN54AC244](#)
- Automotive : [SN74AC244-Q1](#), [SN74AC244-Q1](#)
- Enhanced Product : [SN74AC244-EP](#), [SN74AC244-EP](#)
- Military : [SN54AC244](#)
- Space : [SN54AC244-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC244DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC244DGSR	VSSOP	DGS	20	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
SN74AC244DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AC244DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AC244NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AC244PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AC244RKSR	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



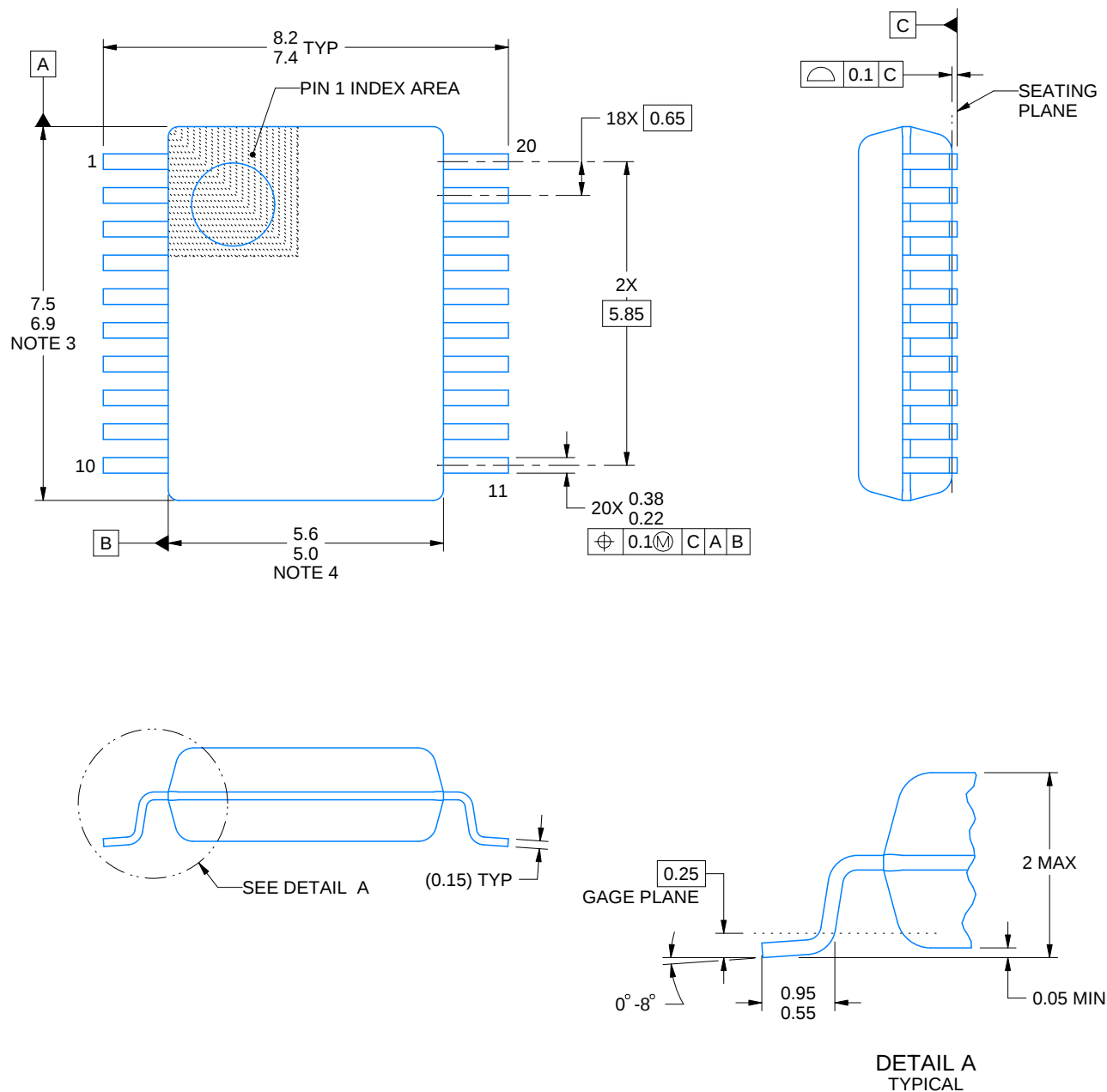
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC244DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74AC244DGSR	VSSOP	DGS	20	5000	353.0	353.0	32.0
SN74AC244DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC244DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC244NSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74AC244PWR	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74AC244RKSR	VQFN	RKS	20	3000	210.0	185.0	35.0



SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

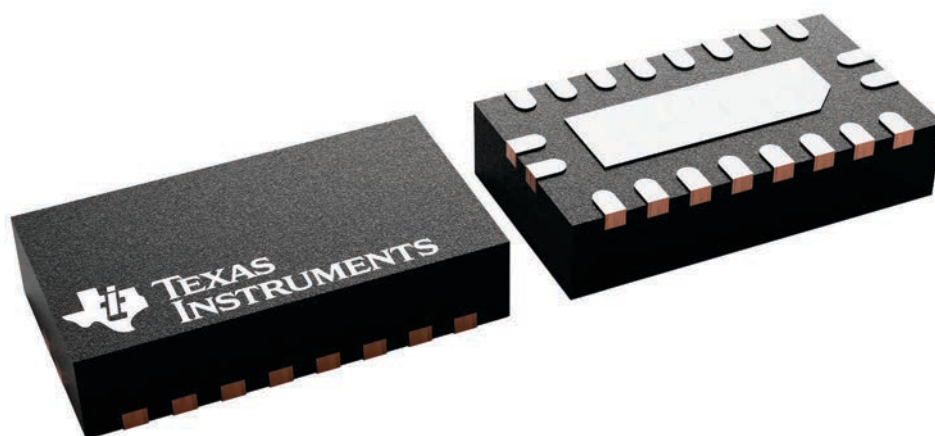
RKS 20

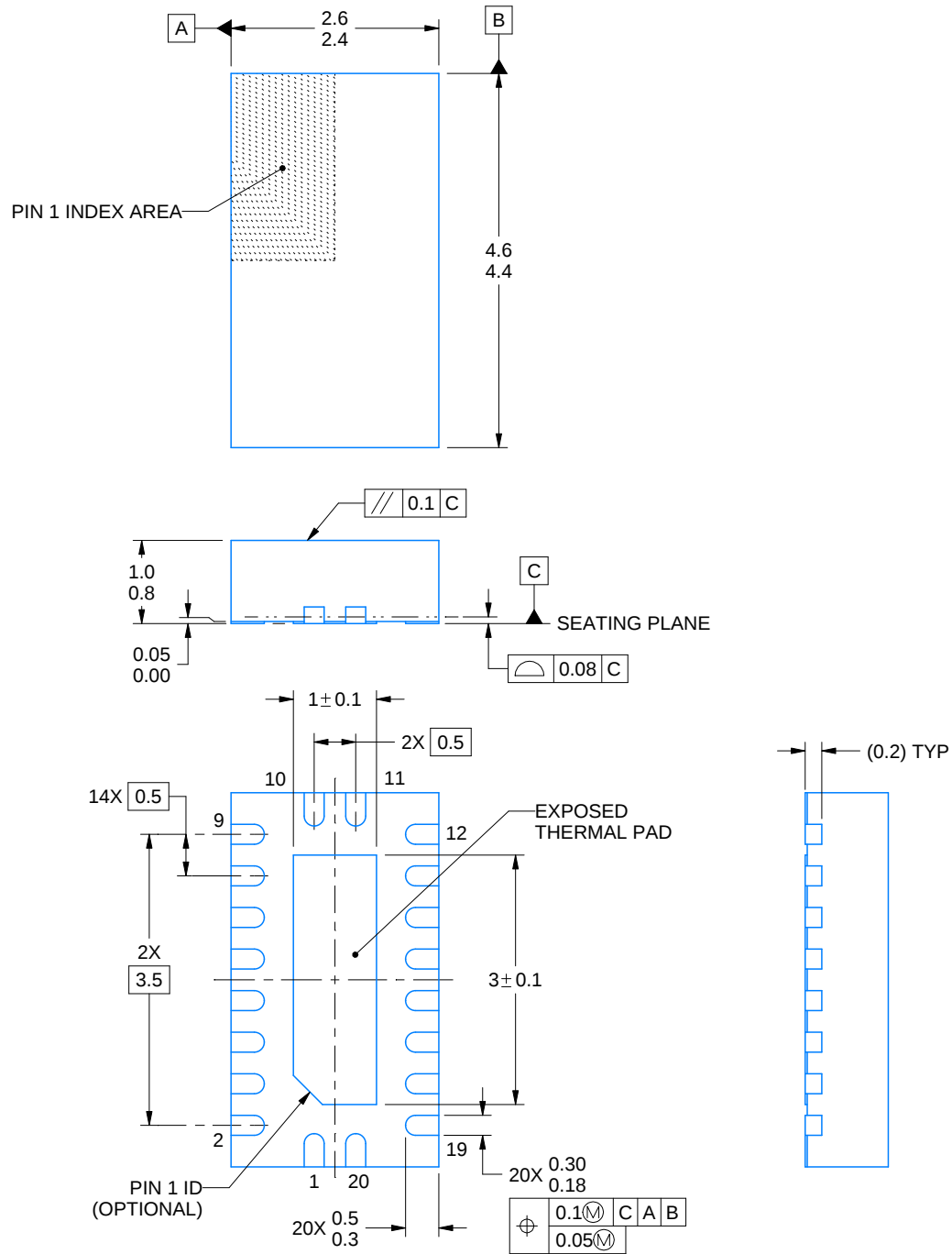
VQFN - 1 mm max height

2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.





4222490/B 02/2021

NOTES:

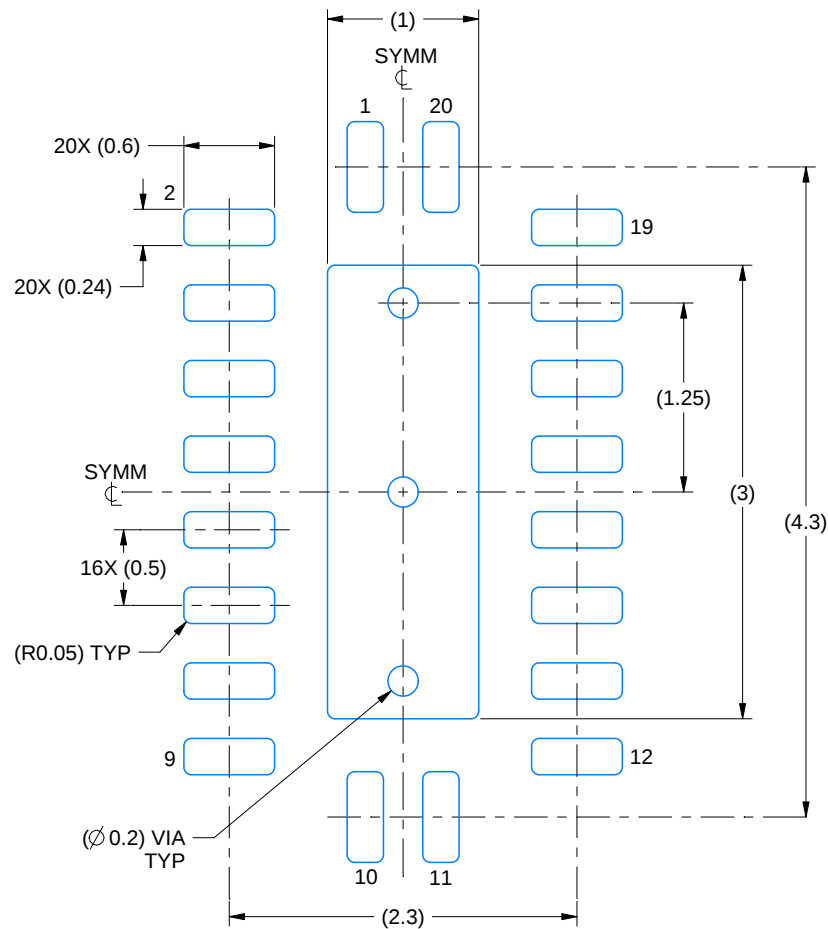
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

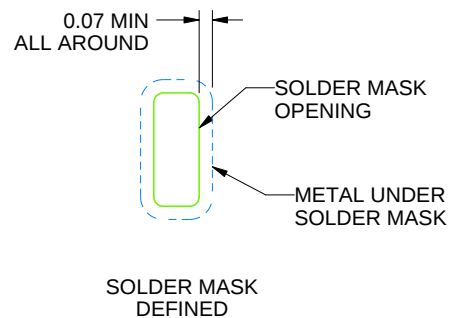
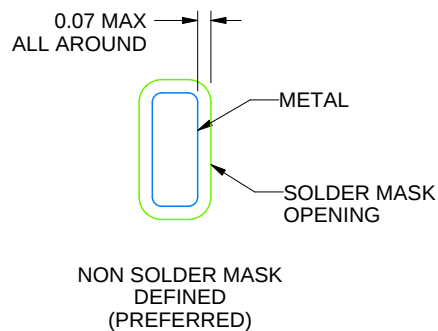
RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4222490/B 02/2021

NOTES: (continued)

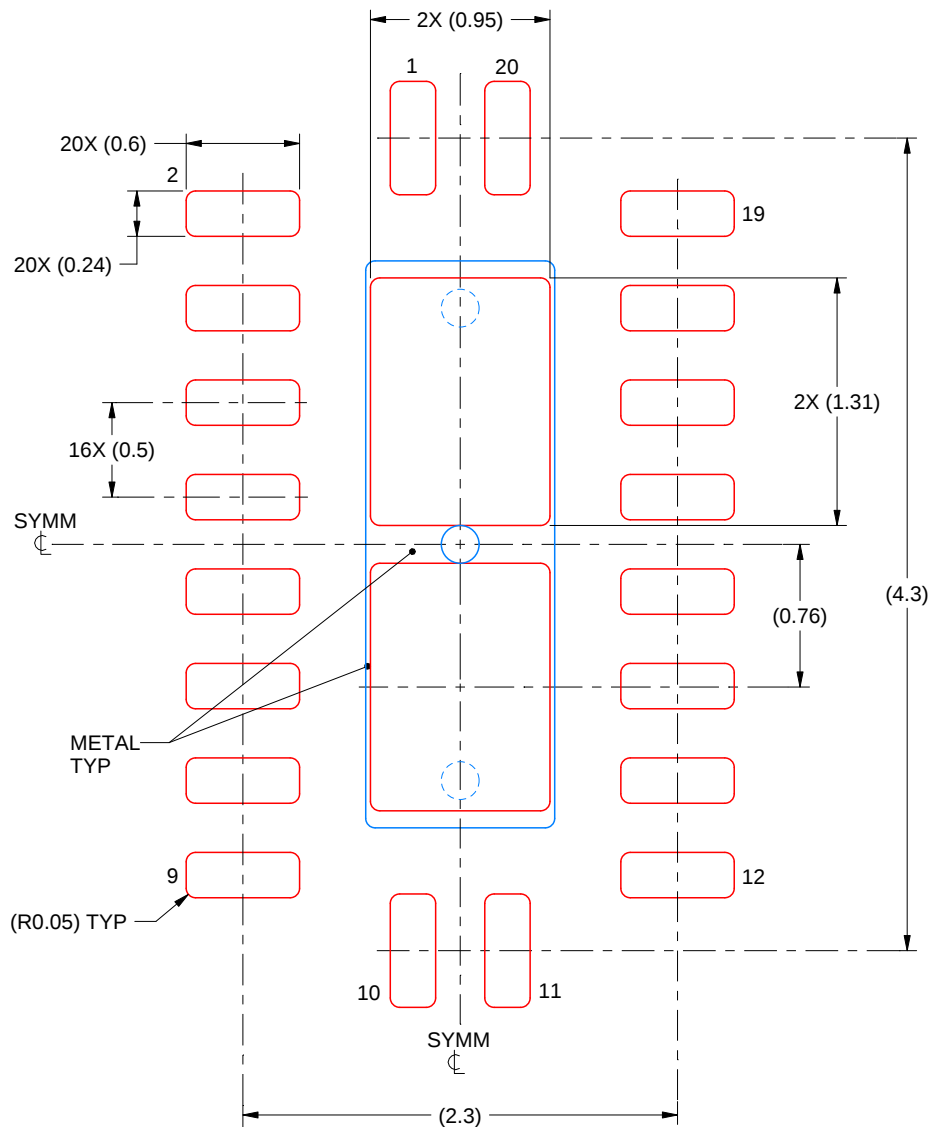
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
83% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

4222490/B 02/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

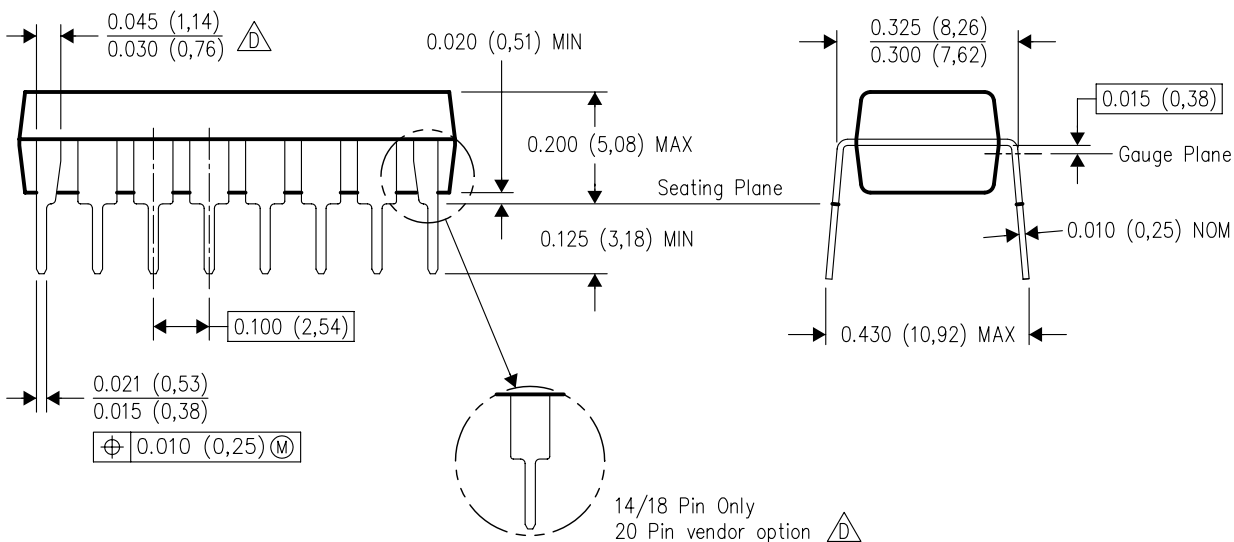
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



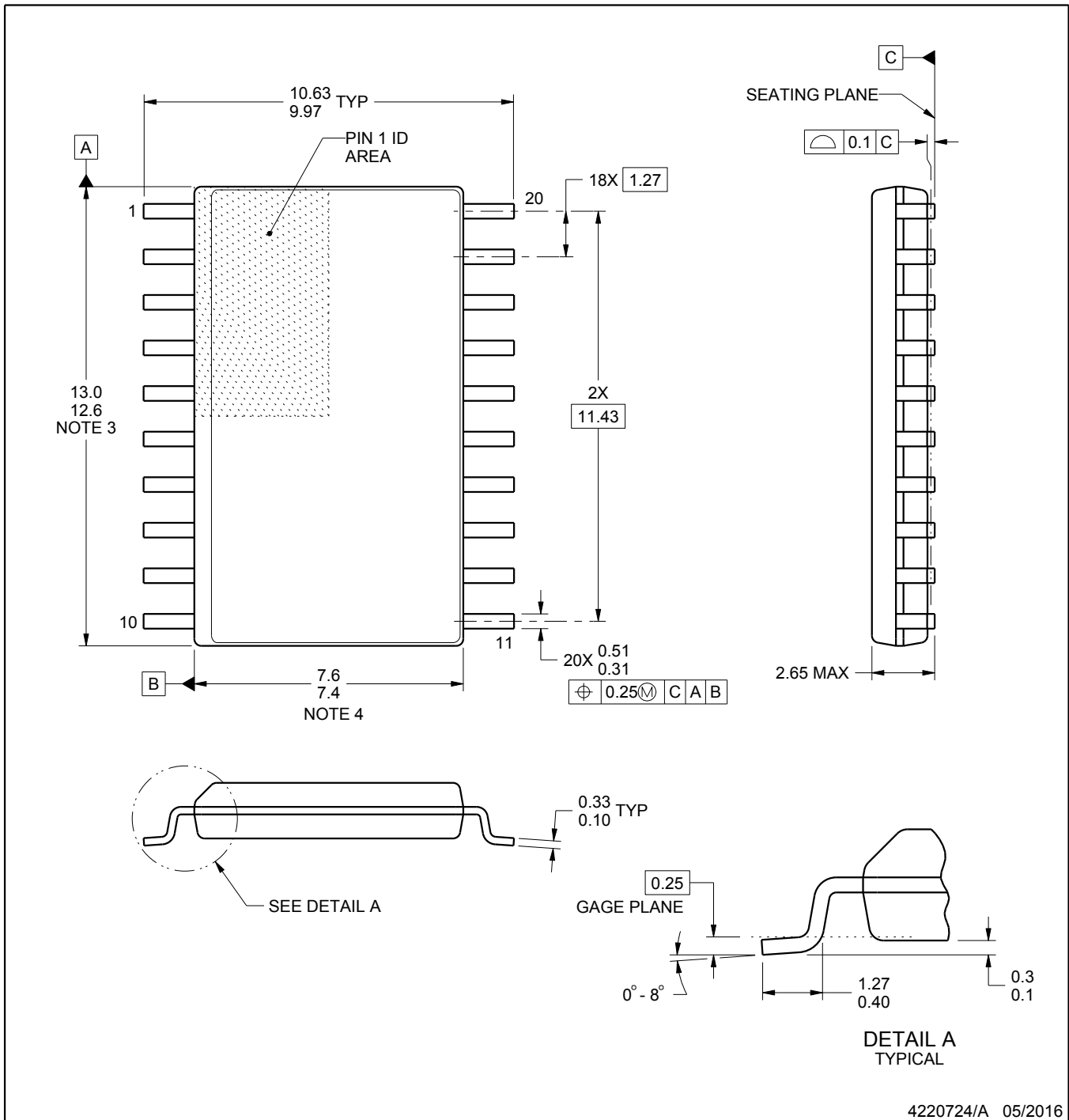
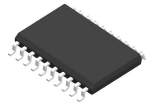
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



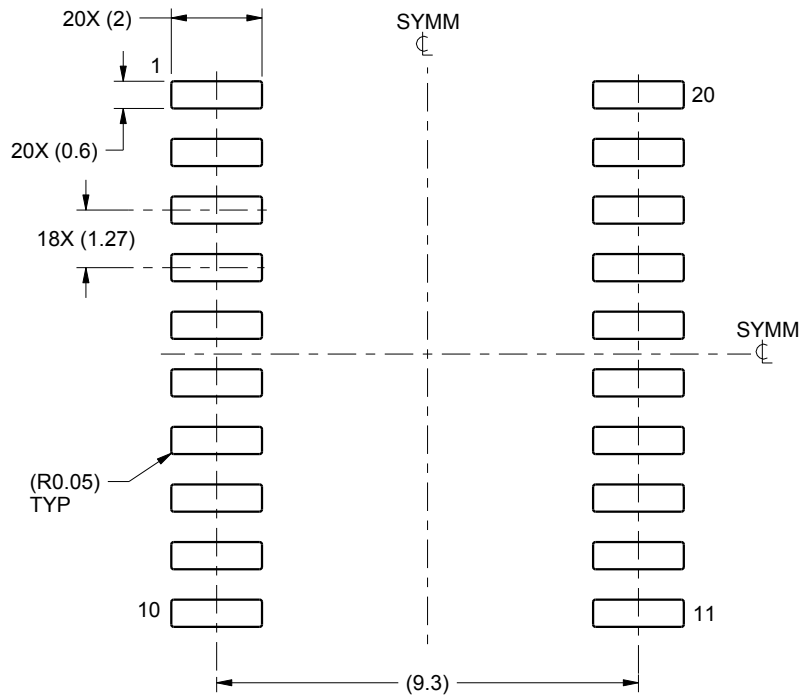
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

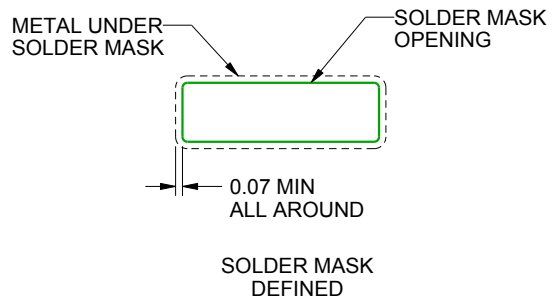
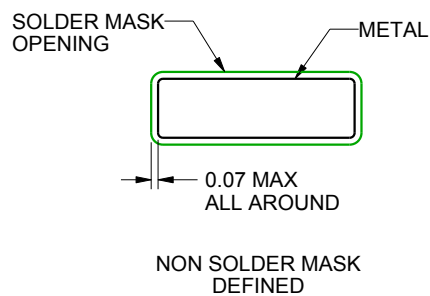
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

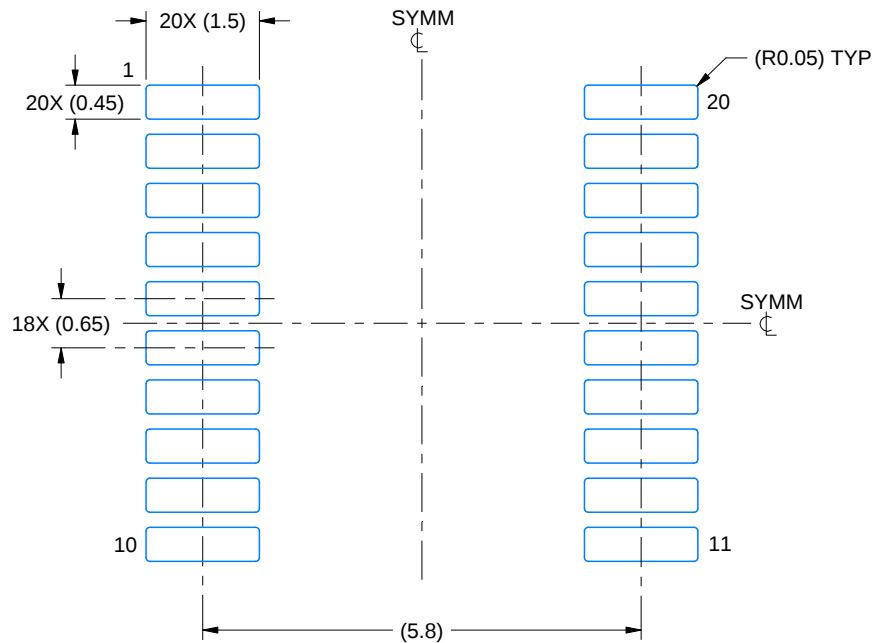
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

EXAMPLE BOARD LAYOUT

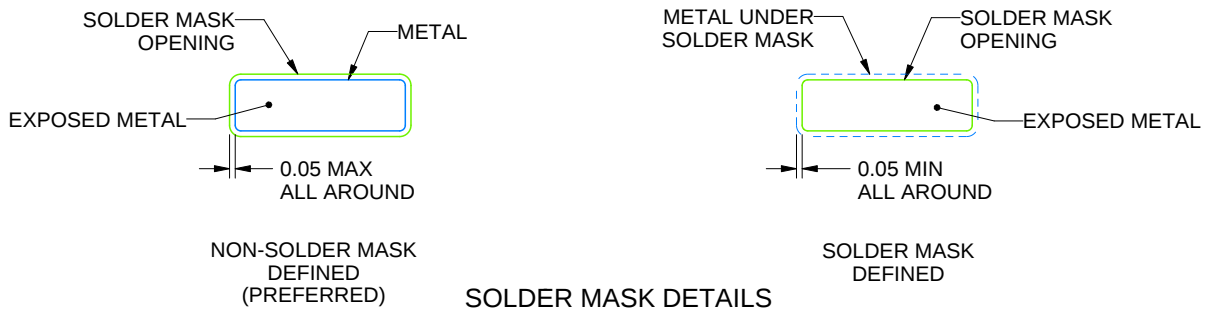
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

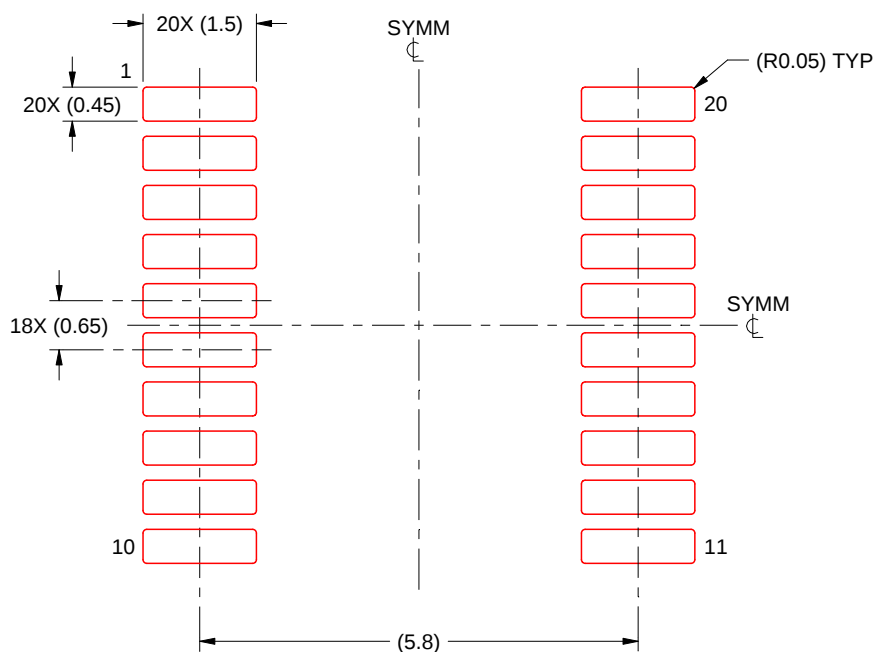
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

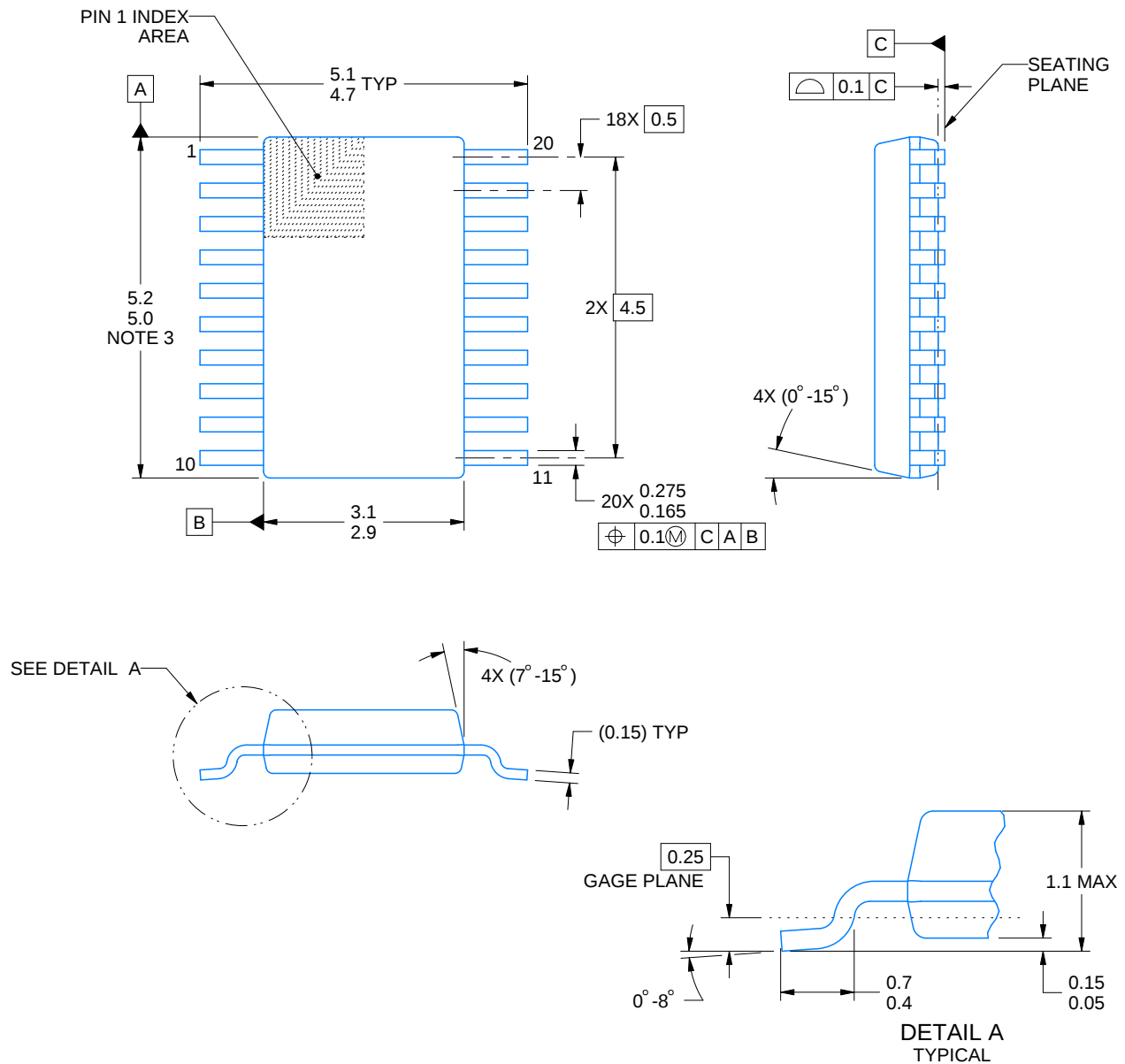


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4226367/A 10/2020

NOTES:

PowerPAD is a trademark of Texas Instruments.

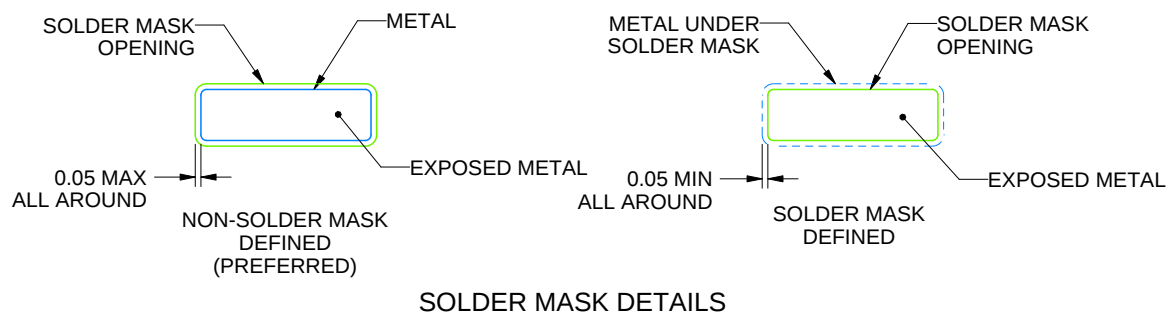
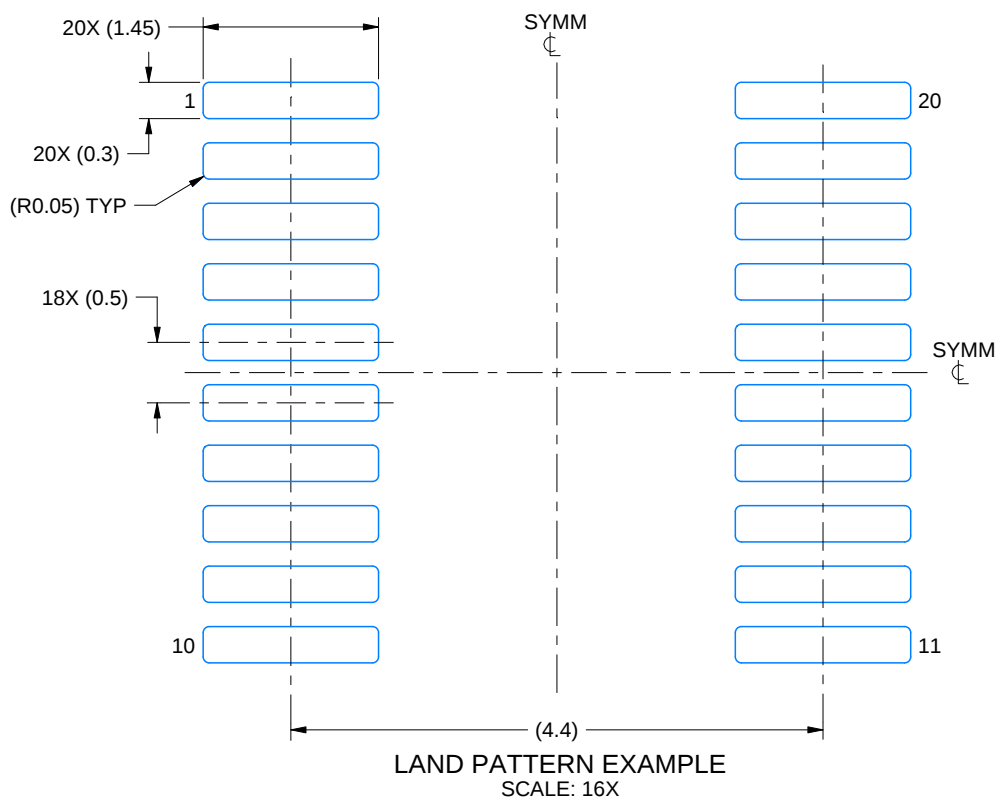
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226367/A 10/2020

NOTES: (continued)

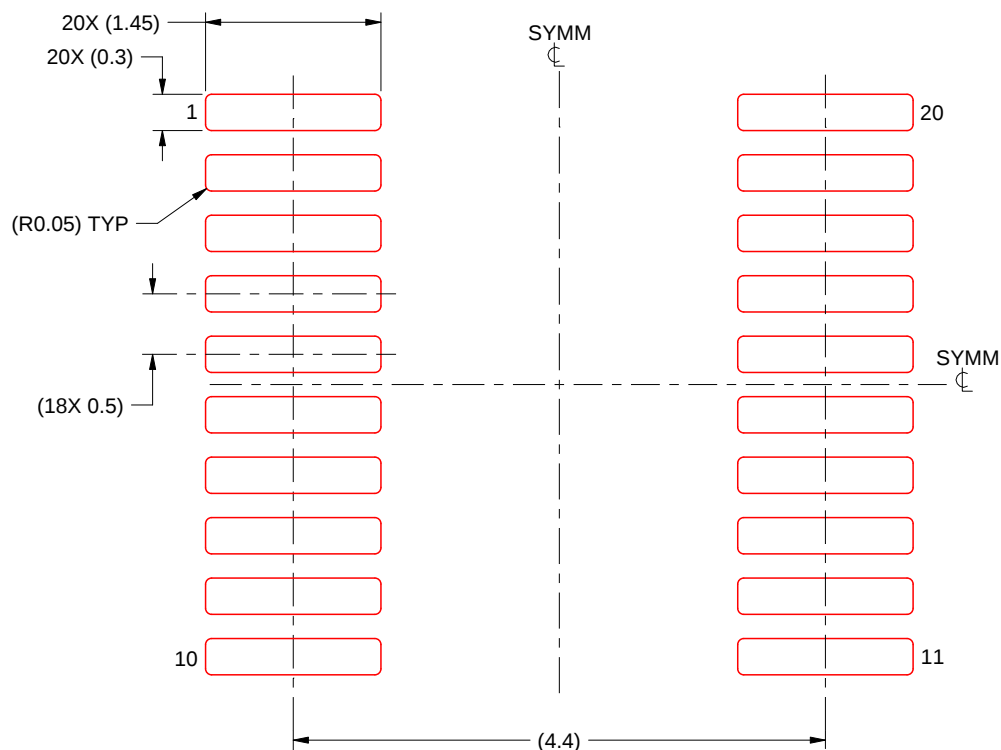
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

4226367/A 10/2020

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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